

TM-GEL-J33



TM-GEL-J33 thermal gel material is designed to be used to replace the thermal gap pad when less stress is required on devices. TM-GEL J33 thermal gel material is very soft gel-like material and has a rather good thermal conductivity and extreme low hardness. It is dispensable to form-in-place filling in air gaps between PC board and heat sinks or a metal chassis.

TM-GEL-J33 is a pre-cured and ready to be used, there is no need to be cured during application. In customer site, therefore it is more effective for both manufacturing and storage. It has a longer self life than normal thermal gel material. It is used by manual extrusion operation or automatically dispensing by robot machine.

Thermal gel

PROPERTIES

Good thermal conductivity
Low hardness
Electrically insulating

TECHNICAL DATA

	UNIT	ITEM
		TM-CT020
Density	g/cc	2,9
Hardness	Shore00	10
Continuos temperature	°C	55 to 200
Thermal conductivity	W/mK	3
Breakdown voltage	V(AC)	8000
Flame rating		V0
Shelf life @ 25°C		24 months
Material		Thermal gel
Colour		Light green